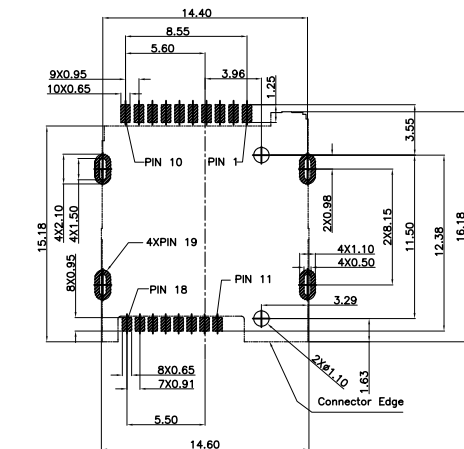
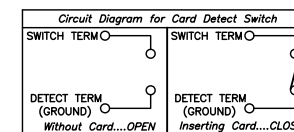


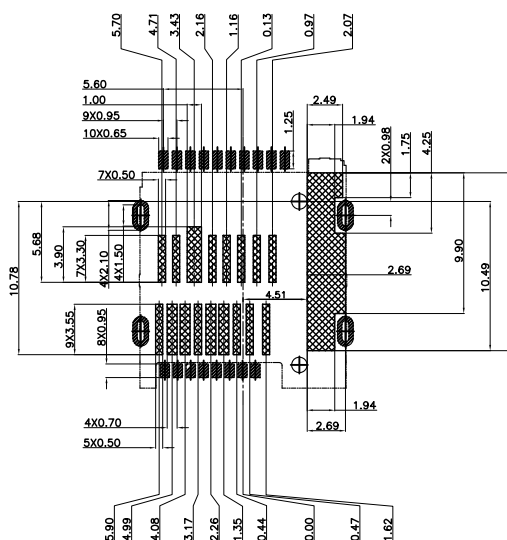
Pin Define

Connector PinNo.	MicroSD 4.0 Card Pin No.	Name	Type	Description
P1	P9	Vcc	S	Supply voltage(1.8V)
P2	P1	DAT2	I/O	Data Line[Bit 2]
P3	P2	CD/DAT3	I/O	Card Detect/Data Line[Bit 3]
P4	P3	CMD	I/O	Command/Response
P5	P4	Vcc1	S	Supply voltage(3.3V)
P6	P5	CLK	I	Clock
P7		CD		
P8	P6	Vss	S	Supply voltage ground
P9	P7	DAT0/RCLK+	I/O	Data Line[Bit 0]/RCLK+
P10	P8	DAT1/RCLK-	I/O	Data Line[Bit 1]/RCLK-
P11	P17	SWIO	I	Single Wire Protocol Interface
P12	P10	Vss	S	Supply voltage ground
P13	P11	DO+	I/O	UHS-II DO+
P14	P12	DO-	I/O	UHS-II DO-
P15	P13	Vss	S	Supply voltage ground
P16	P14	D1-	I/O	UHS-II D1-
P17	P15	D1+	I/O	UHS-II D1+
P18	P16	Vss	S	Supply voltage ground
P19	GND	Vss	S	Supply voltage ground



PCB PATTERN LAYOUT
(GENERAL TOLERANCE:±0.05)

- PAD
- No trace, No test point, No via hole, No ground area



Specification

*Electrical Characteristics:

- Contact Current Rating: 0.5 Amperes.
- Dielectric Withstanding Voltage: AC500Vrms.
- Insulation Resistance: 1000 MΩ Minimum.
- Contact Resistance: 100 mΩ Maximum.

*Environmental:

- Operating Temperature: -25°C~+85°C.

*Material:

- Insulator: HI-Temp Plastic Black UL 94V-0 .
- Contact: Copper Alloy.
- Shell: Stainless Steel.

*PATING:

- 2-1.CONTACT:CONTACT AREA AU 1U" OVER NI 50U";
SOLDER TAIL AREA: MATTED TIN 100U"MIN, OVER NI 50".
- 2-2.SHELL:SOLDERABILITY OVER PLATING NI 30U" OVER ALL.



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X." ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF PUSH 4.0卡座 1.45H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. : HYCW154-TF18-145B
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO. : HYC-2502241751
			SHEET NO. : 1 OF 1